



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. 09/360,292 ✓
 Filing Date July 22, 1999 ✓
 Inventor Sujit Sharan et al. ✓
 Assignee Micron Technology, Inc. ✓
 Group Art Unit 1746
 Examiner S. Ahmed
 Attorney's Docket No. MI22-1106
 Title: Plasma Etching Process (as Amended)

RESPONSE TO SEPTEMBER 25, 2001 OFFICE ACTION

To: Box Non-Fee Amendment
 Assistant Commissioner for Patents
 Washington, D.C. 20231

From: Mark S. Matkin (Tel. 509-624-4276; Fax 509-838-3424)
 Wells, St. John, Roberts, Gregory & Matkin P.S.
 601 West First Avenue, Suite 1300
 Spokane, WA 99201-3828

Sir:

Responsive to the Office Action dated September 25, 2001, Applicant amends and remarks as follows:

AMENDMENTS**In the Title:**

Please replace the title with the following: --PLASMA ETCHING PROCESS--.

In the Claims:

Please cancel claims 1-14, 25-34 and 42-60 without prejudice.

TC 2800 MAIL ROOM
 RECEIVED
 MAR 20 2002
 3/29/02


RECEIVED
 MAR 26 2002
 TC 1700

REMARKS

The Examiner has required restriction under 35 U.S.C. § 121 between claims 1-14 and 25-34 (Group I - drawn to a process for etching a carbon containing material), claims 15-24 and 35-41 (Group II - drawn to an etching process), claims 42-53 (Group III - drawn to an etching/deposition process), and claims 54-60 (Group IV - drawn to a process of forming a conductive contact). Applicant hereby elects without traverse claims 15-24 and 35-41 (Group II) for prosecution on the merits. Accordingly, claims 1-14, 25-34 and 42-60 (Groups I, III and IV) have been canceled without prejudice.

Respectfully submitted,

Dated: 10-19-01

By: 
Mark S. Matkin
Reg. No. 32,268